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No. 1043 P. 1

Attorney Docket No.: CPAC 1017-5
Application No. 10/632,552

SEP 05 2006

PATENT

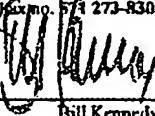
IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

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C.C.
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Applicant: Marcos KARNEZOS)
Application No.: 10/632,552)
Filed: August 2, 2003)
Title: Semiconductor multi-package module having)
package stacked over die-up flip chip)
ball grid array package and having wire)
bond interconnect between stacked packages)

) CERTIFICATE OF FACSIMILE TRANSMISSION

I hereby certify that this correspondence is being facsimile transmitted to
Examiner, Chris C. Chu in the United States Patent and Trademark Office, at
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Signed 
Bill Kennedy

MAIL STOP AF
COMMISSIONER FOR PATENTS
P.O Box 1450
ALEXANDRIA, VA 22313-1450

AMENDMENT

Dear Sir:

In response to the Office action mailed July 5, 2006, kindly amend the application as follows.

Amendments to the Claims are reflected in the Listing of Claims which begins on page 2 of this paper.

Remarks begin on page 5 of this paper.